

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Czjakowski, et al.

Title: RADIATION SHIELDING OF
THREE DIMENSIONAL MULTI-
CHIP MODULES

Appl. No.: Unknown

Filing Date: 08/18/2003

Examiner: Unknown

Art Unit: Unknown

CERTIFICATE OF EXPRESS MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service's "Express Mail Post Office To Addressee" service under 37 C.F.R. § 1.10 on the date indicated below and is addressed to: Commissioner for Patents, PO Box 1450, Alexandria, Virginia 22313-1450.

EL990323029 US August 18, 2003
(Express Mail Label Number) (Date of Deposit)

Line Gauthier
(Printed Name)


(Signature)

Mail Stop PATENT APPLICATION
Commissioner for Patents
PO Box 1450
Alexandria, Virginia 22313-1450

Sir:

Applicants submit herewith on Form PTO/SB/08 a listing of the documents cited by or submitted to the U.S. PTO in parent application Serial No. 09/878,683; 08/221,506; 08/372,289; 08/788,134; and 09/109,954, filed 06/09/2001; 04/01/1994; 01/13/1995; 01/24/1997; and 07/02/1998, respectively. As provided in 37 CFR § 1.98(d), copies of the documents are not being provided since they were previously submitted to the United States Patent & Trademark Office in the above-identified parent application.

The submission of any document herewith, which is not a statutory bar, is not intended as an admission that such document constitutes prior art against the claims of the present application or that such document is considered material to patentability as defined in 37 CFR § 1.56(b). Applicants do not waive any rights to take any action which would be appropriate to antedate or otherwise remove as a competent reference any

document which is determined to be a *prima facie* art reference against the claims of the present application.

TIMING OF THE DISCLOSURE

The listed documents are being submitted in compliance with 37 CFR §1.97(b), within three (3) months of the filing date of the application.

RELEVANCE OF EACH DOCUMENT

All of the documents are in English.

Applicants respectfully request that any listed document be considered by the Examiner and be made of record in the present application and that an initialed copy of Form PTO/SB/08 be returned in accordance with MPEP §609.

The Commissioner is hereby authorized to charge any additional fees which may be required regarding this application under 37 CFR §§ 1.16-1.17, or credit any overpayment, to Deposit Account No. 50-0872. Should no proper payment be enclosed herewith, as by a check being in the wrong amount, unsigned, post-dated, otherwise improper or informal or even entirely missing, the Commissioner is authorized to charge the unpaid amount to Deposit Account No. 50-0872.

Date: August 18, 2003

Respectfully submitted,

FOLEY & LARDNER
Customer Number: 30542



30542

PATENT TRADEMARK OFFICE

Telephone: (312) 832-4553
Facsimile: (312) 832-4700

By Sanjeev K. Dhand

Sanjeev K. Dhand
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Registration No. 37,268

Attorney Docket No. 70638

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Czjakowski, et al.
Serial No.: 09/878,683
Filed: 06/9/2001
For: RADIATION SHIELDING
OF THREE DIMENSIONAL
MULTI-CHIP MODULES
Group Art
Unit: TBD
Examiner: TBD

I hereby certify that this paper is being
deposited with the United States Postal
Service as first class mail in an envelope
addressed to: Commissioner for Patents,
Washington, D.C. 20231, on this date.

11/9/01


Date Thomas F. Lebans
Registration No. 38,221
Attorney for Applicant(s)

**INFORMATION DISCLOSURE STATEMENT IN ACCORDANCE
WITH 37 C.F.R. §§1.97-1.98**

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This Information Disclosure Statement is being made
under 37 C.F.R. §1.97(b).

In accordance with the duty of disclosure imposed by
37 C.F.R. §1.56 to inform the Patent Office of all
references known by Applicant or Applicant's
representative that may be material to the examination of
the subject application, Applicant's representative
hereby provides this Information Disclosure Statement
that is prepared in accordance with 37 C.F.R.
§§1.97-1.98.

The material listed on PTO-1449 as items AA
through AU, inclusive, and items AW through DP,
inclusive, were made of record in U.S. patent application
Serial Number 09/109,954, filed July 2, 1998, for
RADIATION SHIELDING OF THREE DIMENSIONAL MULTI-CHIP

MODULES, to Czjakowski, to which this application claims priority and thus, copies of these items are not required as per C.F.R. §1.98(d).

A copy of the material listed on PTO-1449 as item AV is provided as per 37 C.F.R §1.98(a).

All twelve of the following references cited in the Form-1449 are in a foreign language. Therefore, the Applicant is supplying the following concise explanations of relevance pursuant to 37 C.F.R. § 1.98 (a).

Japanese Patent Publications No. 60-180150 appears to disclose a semiconductor device enclosed within a plastic package, and surrounded by a thin metallic plating to absorb or collect unwanted electro-magnetic interference (EMI).

Japanese Patent Publication No. 61-4249 appears to disclose a spot shielded semiconductor device which utilizes a single-layer shield film.

Japanese Patent Publication No. 4-94560 appears to disclose a semiconductor device enclosed within a plastic package and surrounded by a grounded metallic plate to absorb or reflect EMI.

Japanese Patent Publication No. 56-103452 appears to disclose a packaged semiconductor device having external leads connected to an internal semiconductor device protected from radiation by projections from a base portion.

Japanese Patent Publication No. 2-237053 appears to disclose a semiconductor device surrounded by an EMI wave absorber material in a metal package.

Japanese Patent Publication No. 62-125651 appears to disclose the use of spot shielding to protect a semiconductor device.

Japanese Patent Publication No. 60-106150 appears to disclose the use of a cap or lid to protect an integrated

circuit chip from radiation. It also appears to disclose the use of a metal shielding sheet within a package as well as outside the package.

Japanese Patent Publication No. 54-4781 appears to disclose the use of a metallic thin film on the inside of a container for containing a semiconductor device. The thin film is used to prevent radiation from making the IC malfunction.

Japanese Patent Publication No. 60-124834 appears to disclose an inspection process to detect defective chips, bonding wire or lead frame of a rejective semiconductor device.

Japanese Patent Publication No. 2-278740 appears to disclose a way of bonding and IC chip to a lead frame with sealing frame and performing resin-sealing of the IC chip in a way to reduce the bonding time.

Japanese Patent Publication No. 4-273200 appears to disclose a shielding device that is on top of a printed wiring board.

French Patent No. 258483 appears to disclose a protective component used with complex circuits in spacecraft. The protective component appears to be successive layers of materials with high and low numbers of charges that protects against ionizing radiation.

English translations have been previously provided for items DA, DB, and DF.

Although these documents are made known to the Patent and Trademark Office in compliance with Applicant's duty of disclosure, such disclosure is not to be construed as an admission by Applicant or Applicant's representative that any of the references is effective as prior art against the subject application. In accordance with 37 CFR 1.97(b), the filing of this Information Disclosure Statement shall not be construed to mean that

IDS
S.N. 09/878,683

-4-

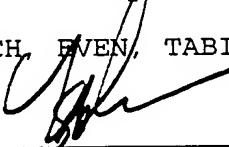
a search has been made or that no other material information as defined in 37 CFR 1.56(a) exists.

Applicant respectfully requests that the Examiner review the foregoing references and that they be made of record in the file history of the above-captioned application.

Respectfully submitted;

FITCH, EVEN, TABIN & FLANNERY

By:


Thomas F. Lebens
Registration No. 38,221

Dated: 9-Nov, 2001

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135 So. LaSalle Street, Suite 900
Chicago, Illinois 60603
Telephone: 858/587-7644

**INFORMATION DISCLOSURE
CITATION IN AN APPLICATION**

Application No.	09/878,683
Filing Date	6/9/01
First Named Inventor	Czjakowski, et al.
Group Art Unit	TBD
Examiner Name	TBD
Sheet 1 of 5	Attorney Docket No. 70638

U.S. PATENT DOCUMENTS

EXAMINE R INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	U.S. PATENT DOCUMENT		NAME OF INVENTOR OR APPLICANT	DATE OF ISSUANCE OR PUBLICATION (MM-DD- YYYY)	CLASS	SUB CLASS	FILING DATE (if appropriate)
			PATENT, PUB., OR APP. NO.	KIND CODE (if known)					
	AA	X	4,663,240		Hajdu, et al.	5/87			4/84
	AB	X	4,979,019		Paquette, et al.	12/90			5/88
	AC	X	5,561,265		Livshits, et al.	10/96			10/94
	AD	X	4,652,465		Koto	3/87			5/85
	AE	X	4,506,108		Kersch, et al.	3/85			4/83
	AF	X	4,833,334		Valy, et al.	5/89			4/87
	AG	X	4,975,762		Stradley, et al.	12/90			6/81
	AH	X	5,317,107		Osorio	5/94			9/92
	AI	X	5,406,117		Dlugoecki, et al.	4/95			12/93
	AJ	X	4,091,407		Williams, et al.	5/78			11/76
	AK	X	5,825,042		Strobel, et al.	10/98			1/95
	AL	X	5,889,316		Strobel, et al.	3/99			2/96
	AM	X	5,880,403		Czajkowski, et al.	3/99			1/97
	AN	X	3,828,425		Manus	8/74			10/70
	AO	X	4,837,448		Sainte Luce Banchelin, et al.	6/89			4/87
	AP	X	3,771,025		Berner	11/73			10/69
	AQ	X	5,206,794		Long	4/93			12/91
	AR	X	5,268,331		Abbott	12/93			1/92
	AS	X	3,706,840		Moyle, et al.	12/72			5/71
	AT	X	3,914,858		Sonoda, et al.	10/75			8/74
	AU	X	4,100,675		Landsittel	7/78			11/76

Form PTO-1449 (Modified) INFORMATION DISCLOSURE CITATION IN AN APPLICATION		Application No.	09/878,683
		Filing Date	6/9/01
		First Named Inventor	Czjakowski, et al.
		Group Art Unit	TBD
		Examiner Name	TBD
Sheet 2 of 5		Attorney Docket No.	70638

U.S. PATENT DOCUMENTS									
EXAMINE R INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	U.S. PATENT DOCUMENT		NAME OF INVENTOR OR APPLICANT	DATE OF ISSUANCE OR PUBLICATION (MM-DD- YYYY)	CLASS	SUB CLASS	FILING DATE (if appropriate)
			PATENT, PUB., OR APP. NO.	KIND CODE (if known)					
	AV		4,167,647		Salera	9/79			5/76
	AW	X	4,173,683		Comizzoli	11/79			4/78
	AX	X	4,250,347		Fierkens	2/81			4/78
	AY	X	4,633,573		Scherer	1/87			5/84
	AZ	X	4,769,344		Sakai, et al.	9/88			1/87
	BA	X	5,139,969		Mori	8/92			7/91
	BB	X	5,527,742		Weiler, et al.	6/96			6/95
	BC	X	5,851,852		Ostop, et al.	12/98			2/96
	BD	X	5,888,850		Havens, et al.	3/99			9/97
	BE	X	5,824,568		Zechman	10/98			7/96
	BF	X	5,780,163		Camilletti, et al.	7/98			6/96
	BG	X	5,096,851		Yamazaki, et al.	3/92			8/90
	BH	X	4,888,449		Crane, et al.	12/89			1/88
	BI	X	4,835,120		Mallik, et al.	5/89			6/88
	BJ	X	4,468,411		Sloan, et al.	8/84			4/82
	BK	X	4,891,687		Mallik, et al.	1/90			1/89
	BL	X	5,561,265		Livshits, et al.	10/96			10/94
	BM	X	4,652,465		Koto, et al.	3/87			5/85
	BN	X	4,979,019		Paquette, et al.	12/90			5/88
	BO	X	4,663,240		Hajdu, et al.	5/87			11/84
	BP	X	5,304,750		Schubert, et al.	10/94			8/89
	BQ	X	5,202,536		Buonanno	4/93			2/92

Form PTO-1449 (Modified)		Application No.	09/878,683
INFORMATION DISCLOSURE CITATION IN AN APPLICATION		Filing Date	6/9/01
		First Named Inventor	Czjakowski, et al.
		Group Art Unit	TBD
		Examiner Name	TBD
		Sheet 3 of 5	Attorney Docket No.

U.S. PATENT DOCUMENTS									
EXAMINE R INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	U.S. PATENT DOCUMENT		NAME OF INVENTOR OR APPLICANT	DATE OF ISSUANCE OR PUBLICATION (MM-DD- YYYY)	CLASS	SUB CLASS	FILING DATE (if appropriate)
			PATENT, PUB., OR APP. NO.	KIND CODE (if known)					
BR	X		4,089,575		Grabbe	5/78			9/76
BS	X		5,151,770		Inoue	9/92			11/90
BT	X		5,239,126		Oshiba	8/93			1/91
BU	X		5,250,845		Runyan	10/93			11/90
BV	X		4,967,315		Schelhorn	10/90			1/90
BW	X		5,770,304		Nakamura	6/98			7/95
BX	X		4,661,837		Sono	4/87			12/85
BY	X		4,839,716		Butt	6/89			6/87
BZ	X		4,953,002		Nelson, et al.	8/90			9/89
CA	X		5,138,430		Gow, III, et al.	8/92			6/91
CB	X		5,149,662		Eichelberger	9/92			2/92
CC	X		5,166,772		Soldner, et al.	11/92			2/91
CD	X		5,294,826		Marcantonio, et al.	3/94			4/93
CE	X		4,935,174		Suzuki	6/90			9/89
CF	X		5,047,260		Durand	9/91			3/90
CG	X		5,180,513		Durand	1/93			1/90
CH	X		5,424,251		Sono, et al.	6/95			9/93
CI	X		5,577,319		Knecht	11/96			3/95
CJ	X		5,589,129		Kato, et al.	12/96			6/95
CK	X		5,610,443		Inagaki, et al.	3/97			9/95
CL	X		4,687,622		Longden	8/87			10/85
CM	X		5,672,918		Kimbrough, et al.	9/97			8/94

Form PTO-1449 (Modified)		Application No.	09/878,683
INFORMATION DISCLOSURE CITATION IN AN APPLICATION		Filing Date	6/9/01
		First Named Inventor	Czjakowski, et al.
		Group Art Unit	TBD
		Examiner Name	TBD
Sheet 4 of 5		Attorney Docket No.	70638

U.S. PATENT DOCUMENTS									
EXAMINER INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	U.S. PATENT DOCUMENT		NAME OF INVENTOR OR APPLICANT	DATE OF ISSUANCE OR PUBLICATION (MM-DD-YYYY)	CLASS	SUB CLASS	FILING DATE (if appropriate)
			PATENT, PUB., OR APP. NO.	KIND CODE (if known)					
	CN	X	5,384,477		Bulucea, et al.	1/95			3/93
	CO	X	5,441,900		Bulucea, et al.	8/95			9/94
	CP	X	5,552,338		Kang	9/96			9/95
	CQ	X	5,714,102		Highum, et al.	2/98			4/95
	CR	X	5,864,088		Sato, et al.	1/99			1/95
	CS	X	5,880,403		Czajkowski, et al.	3/99			1/97
	CT	X	5,294,826		Marcantonio, et al.	3/94			4/93

FOREIGN PATENT DOCUMENTS									
EXAMINER INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	FOREIGN PATENT DOCUMENT			DATE OF PUBLICATION (MM-DD-YYYY)	CLASS	SUB CLASS	TRANSLATION
			COUNTRY OR OFFICE (two-letter code)	DOCUMENT NO.	KIND CODE (if known)				
	CU	X	JP	56/103,452		8/81			
	CV	X	JP	60/180,150		9/85			
	CW	X	JP	61/004,249		1/86			
	CX	X	JP	62/125,651		6/87			
	CY	X	JP	2,237,053		9/90			
	CZ	X	JP	4,094,560		3/92			
	DA	X	JP	61/004,250		1/86			
	DB	X	JP	57/095,650		6/82			
	DC	X	JP	60/106,150		6/85			

Form PTO-1449 (Modified)		Application No.	09/878,683
INFORMATION DISCLOSURE CITATION IN AN APPLICATION		Filing Date	6/9/01
		First Named Inventor	Czjakowski, et al.
		Group Art Unit	TBD
		Examiner Name	TBD
Sheet 5 of 5		Attorney Docket No.	70638

FOREIGN PATENT DOCUMENTS										
EXAMINER INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	FOREIGN PATENT DOCUMENT			DATE OF PUBLICATION (MM-DD-YYYY)	CLASS	SUB CLASS	TRANSLATION	
			COUNTRY OR OFFICE (two-letter code)	DOCUMENT NO.	KIND CODE (if known)				YES	NO
	DD	X	JP	54/004,781		7/80				
	DE	X	FR	2,584,863		1/87				
	DF	X	EP	0,160,327		11/85				
	DG	X	JP	60/124,834		7/85				
	DH	X	JP	4,273,200		9/92				
	DI	X	JP	2,278,740		11/90				

OTHER DOCUMENTS -- NON PATENT LITERATURE DOCUMENTS			
EXAMINER DM INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.
	DJ	X	"Electronics Packaging and Production", p 26-27
	DK	X	"Electronic materials and Processes, Consulting and Short Courses", p 1-3
	DL	X	"Electronic Materials Handbook", p 470-483
	DM	X	"Electronic Packaging and Interconnection Handbook", p 6.41- 6.49
	DN	X	M.P. Baze, et al., "Latch-Up Paths in Bipolar Integrated Circuits", IEEE Transactions on Nuclear Science, December 1986, Vol. NS-33 No. 6
	DO	X	A. H. Johnston, et al., " The Effect of Temperature on Single-Particle Latch-Up", IEEE Transactions on Nuclear Science, December 1991, Vol. 38, No. 6
	DP	X	Song, et al., "Parametric Investigation of Latch-Up Sensitivity in 1.25 μ m CMOS Technology", IEEE Transactions on Nuclear Science, December 1987, Vol. NS 34 No. 6

Examiner Signature		Date Considered	
-----------------------	--	--------------------	--

*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP §609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

**INFORMATION DISCLOSURE
CITATION IN AN APPLICATION**

Filing Date

6/9/01

First Named Inventor

Czjakowski, et al.

Group Art Unit

2831

Examiner Name

Ngo, H.

Sheet 1 of 2

Attorney Docket No.

70638

U.S. PATENT DOCUMENTS

EXAMINER INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	U.S. PATENT DOCUMENT		NAME OF INVENTOR OR APPLICANT	DATE OF ISSUANCE OR PUBLICATION (MM-DD-YYYY)	CLASS	SUB CLASS	FILING DATE (if appropriate)
			PATENT, PUB., OR APP. NO.	KIND CODE (if known)					

FOREIGN PATENT DOCUMENTS

EXAMINER INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	FOREIGN PATENT DOCUMENT			DATE OF PUBLICATION (MM-DD-YYYY)	CLASS	SUB CLASS	TRANSLATION	
			COUNTRY OR OFFICE (two-letter code)	DOCUMENT NO.	KIND CODE (if known)				YES	NO
	DQ		JP	56/103,452		8/81				
	DR		JP	60/180,150		9/85				
	DS		JP	61/004,249		1/86				
	DT		JP	62/125,651		6/87				
	DU		JP	2,237,053		9/90				
	DV		JP	4,094,560		3/92				
	DW		JP	61/004,250		1/86				
	DX		JP	57/095,650		6/82				
	DY		JP	60/106,150		6/85				
	DZ		JP	54/004,781		7/80				
	EA		FR	2,584,863		1/87				
	EB		EP	0,160,327		11/85				
	EC		JP	60/124,834		7/85				
	ED		JP	4,273,200		9/92				
	EF		JP	2,278,740		11/90				

Form PTO-1449 (Modified)		Application No.	178,683
INFORMATION DISCLOSURE CITATION IN AN APPLICATION		Filing Date	6/9/01
		First Named Inventor	Czjakowski, et al.
		Group Art Unit	2831
		Examiner Name	Ngo, H.
Sheet 2 of 2		Attorney Docket No.	70638

OTHER DOCUMENTS – NON PATENT LITERATURE DOCUMENTS			
EXAMINER D M INITIALS*	CITE NO.	COPY NOT ENCLOSED PER 37 CFR § 1.98(d)	Include name of the author (in CAPITAL LETTERS), title of the article (when appropriate), title of the item (book, magazine, journal, serial, symposium, catalog, etc.), date, page(s), volume-issue number(s), publisher, city and/or country where published.
	EG		“Electronics Packaging and Production”, p 26-27
	EH		“Electronic materials and Processes, Consulting and Short Courses”, p 1-3
	EI		“Electronic Materials Handbook”, p 470-483
	EJ		“Electronic Pakcaging and Interconnection Handbook”, p 6.41- 6.49
	EK		M.P. Baze, et al., “Latch-Up Paths in Bipolar Integrated Circuits”, IEEE Transactions on Nuclear Science, December 1986, Vol. NS-33 No. 6
	EL		A. H. Johnston, et al., “ The Effect of Temperature on Single-Particle Latch-Up”, IEEE Transactions on Nuclear Science, December 1991, Vol. 38, No. 6
	EM		Song, et al., “Parametric Investigation of Latch-Up Sensitivity in 1.25 µm CMOS Technology”, IEEE Transactions on Nuclear Science, December 1987, Vol. NS 34 No. 6

Examiner Signature		Date Considered
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*EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP §609. Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.

EXHIBIT A

DOCKET NO. 66229

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant(s): Czjakowski, et al.
Serial No.: 09/109,954
Filed: 07/02/98
For: RADIATION SHIELDING
OF THREE DIMENSIONAL
MULTI-CHIP MODULES
Art Unit: 2831
Examiner: Ngo, H.

I hereby certify that this paper is being deposited with
the United States Postal Service as first class mail in
an envelope addressed to: Commissioner for Patents,
Washington, D.C. 20231, on this date.
18-AUGUST-2011
Date Thomas F. Lebans
Registration No. 38,221
Attorney for Applicant(s)

INFORMATION DISCLOSURE STATEMENT IN ACCORDANCE WITH 37 C.F.R. §§1.97-1.98

Commissioner for Patents
Washington, D.C. 20231

Dear Sir:

This Information Disclosure Statement is being made under
37 C.F.R. §1.97(c). Thus, a check for \$240.00 is enclosed as
per 37 C.F.R. §§1.17(p).

Any additional fees that may be due in connection with
filing this Information Disclosure Statement may be charged to
Deposit Account No. 06-1135.

In accordance with the duty of disclosure imposed by 37
C.F.R. §1.56 to inform the Patent Office of all references
known by Applicant or Applicant's representative that may be
material to the examination of the subject application,
Applicant's representative hereby provides this Information
Disclosure Statement that is prepared in accordance with 37
C.F.R. §§1.97-1.98.

The material listed on PTO-1449 as items AA through AI,
inclusive, and items CT through CY, inclusive, were made of
record in U.S. patent application Serial Number 08/372,289,
filed January 1, 1995, to which this application claims

INFORMATION DISCLOSURE STATEMENT
Serial No. 09/109,954

priority and thus, copies of these items are not required as per C.F.R. §1.98(d).

Copies of the materials listed on PTO-1449 as items AJ through CS, inclusive, and items CZ through DO, inclusive, are provided as per 37 C.F.R. §1.98(a).

All twelve of the following references cited in the Form-1449 are in a foreign language. Therefore, the Applicant is supplying the following concise explanations of relevance pursuant to 37 C.F.R. § 1.98 (a).

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Japanese Patent Publication No. 61-4249 appears to disclose a spot shielded semiconductor device which utilizes a single-layer shield film.

Japanese Patent Publication No. 4-94560 appears to disclose a semiconductor device enclosed within a plastic package and surrounded by a grounded metallic plate to absorb or reflect EMI.

Japanese Patent Publication No. 56-103452 appears to disclose a packaged semiconductor device having external leads connected to an internal semiconductor device protected from radiation by projections from a base portion.

Japanese Patent Publication No. 2-237053 appears to disclose a semiconductor device surrounded by an EMI wave absorber material in a metal package.

Japanese Patent Publication No. 62-125651 appears to disclose the use of spot shielding to protect a semiconductor device.

Japanese Patent Publication No. 60-106150 appears to disclose the use of a cap or lid to protect an integrated circuit chip from radiation. It also appears to disclose the

INFORMATION DISCLOSURE STATEMENT
Serial No. 09/109,954

use of a metal shielding sheet within a package as well as outside the package.

Japanese Patent Publication No. 54-4781 appears to disclose the use of a metallic thin film on the inside of a container for containing a semiconductor device. The thin film is used to prevent radiation from making the IC malfunction.

Japanese Patent Publication No. 60-124834 appears to disclose an inspection process to detect defective chips, bonding wire or lead frame of a rejective semiconductor device.

Japanese Patent Publication No. 2-278740 appears to disclose a way of bonding and IC chip to a lead frame with sealing frame and performing resin-sealing of the IC chip in a way to reduce the bonding time.

Japanese Patent Publication No. 4-273200 appears to disclose a shielding device that is on top of a printed wiring board.

French Patent No. 258483 appears to disclose a protective component used with complex circuits in spacecraft. The protective component appears to be successive layers of materials with high and low numbers of charges that protects against ionizing radiation.

English translations have been provided for items CZ, DA and DE.

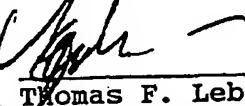
Although these documents are made known to the Patent and Trademark Office in compliance with Applicant's duty of disclosure, such disclosure is not to be construed as an admission by Applicant or Applicant's representative that any of the references is effective as prior art against the subject application. In accordance with 37 CFR 1.97(b), the filing of this Information Disclosure Statement shall not be construed to mean that a search has been made or that no other material information as defined in 37 CFR 1.56(a) exists.

INFORMATION DISCLOSURE STATEMENT
Serial No. 09/109,954

Applicant respectfully requests that the Examiner review the foregoing references and that they be made of record in the file history of the above-captioned application.

Respectfully submitted,

FITCH, EVEN, TABIN & FLANNERY

By: 

Thomas F. Lebens

Registration No. 38,221

Dated: 18 AUGUST, 2000

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Chicago, Illinois 60603
Telephone: 858/552-1311

Form PTO-1449 (Modified)								Docket Number 66229		Application Number 09/109,954			
								Applicant Czjakowski, et al.					
INFORMATION DISCLOSURE CITATION IN AN APPLICATION (Use several sheets if necessary)								Filing Date 07/02/98		Group Art Unit 2831			
U.S. PATENT DOCUMENTS													
Examiner Initial		DOCUMENT NUMBER							DATE	NAME	CLASS	SUB CLASS	FILING DATE
AA		4	6	6	3	2	4	0	5/1987	Hajdu et al.	428	545	4/1984
AB		4	9	7	9	0	1	9	12/1990	Paquette et al.	257	690	5/1988
AC		5	5	6	1	2	6	5	3/1993	Livshits et al.	174	35gc	10/1994
AD		4	6	5	2	4	6	5	3/1987	Koto	427	216	5/1985
AE		4	5	0	6	1	0	8	3/1985	Kersch et al.	174	52	4/1983
AF		4	8	3	3	3	3	4	5/1989	Valy et al.	250	515.1	4/1987
AG		4	9	7	5	7	6	2	12/1990	Stradley et al.	257	660	6/1981
AH		5	3	1	7	1	0	7	5/1994	Osorio	174	52.4	9/1992
AI		5	4	0	6	1	1	7	4/1995	Dlugoecki et al.	257	659	12/1993
AJ		4	0	9	1	4	0	7	5/1978	Williams et al.	357	54	11/1976
AK		5	8	2	5	0	4	2	10/1998	Strobel et al.	250	515.1	1/1995
AL		5	8	8	9	3	1	6	3/1999	Strobel et al.	257	659	2/1996
AM		5	8	8	0	4	0	3	3/1999	Czajkowski et al.	174	35R	1/1997
AN		3	8	2	8	4	2	5	8/1974	Manus	29	590	10/1970
AO		4	8	3	7	4	4	8	6/1989	Sainte Luce Banchelin et al.	250	519.1	4/1987
AP		3	7	7	1	0	2	5	11/1973	Berner	317	234R	10/1969
AQ		5	2	0	6	7	9	4	4/1993	Long	257	675	12/1991
AR		5	2	6	8	3	3	1	12/1993	Abbott	437	225	1/1992
AS		3	7	0	6	8	4	0	12/1972	Moyle et al.	174	52PE	5/1971
AT		3	9	1	4	8	5	8	10/1975	Sonoda et al.	29	588	8/1974
AU		4	1	0	0	6	7	5	7/1978	Landsittel	29	627	11/1976
AV		4	1	7	3	6	8	3	11/1979	Comizzoli	428	447	4/1978
AW		4	2	5	0	3	4	7	2/1981	Fierkens	174	52	4/1978
AX		4	6	3	3	5	7	3	1/1987	Scherer	29	589	5/1984
AY		4	7	6	9	3	4	4	9/1988	Sakai et al.	437	216	1/1987
AZ		5	1	3	9	9	6	9	8/1992	Mori	437	183	7/1991
BA		5	5	2	7	7	4	2	6/1996	Weiler et al.	437	211	6/1995

	BB	5	8	5	1	8	5	2	12/1998	Ostop et al.	438	106	2/1996
	BC	5	8	8	8	8	5	0	3/1999	Havens et al.	438	127	9/1997
	BD	5	8	2	4	5	6	8	10/1998	Zechman	438	112	7/1996
	BE	5	7	8	0	1	6	3	7/1998	Camilletti et al.	428	446	6/1996
	BF	5	0	9	6	8	5	1	3/1992	Yamazaki et al.	437	205	8/1990
	BG	4	8	8	8	4	4	9	12/1989	Crane et al.	174	52.4	1/1988
	BH	4	8	3	5	1	2	0	5/1989	Mallik et al.	437	209	6/1988
	BI	4	4	6	8	4	1	1	8/1984	Sloan et al.	427	8	4/1982
	BJ	4	8	9	1	6	8	7	1/1990	Mallik et al.	357	70	1/1989
	BK	5	5	6	1	2	6	5	10/1996	Livshits et al.	174	35GC	10/1996
	BL	4	6	5	2	4	6	5	3/1987	Koto et al.	427	216	5/1985
	BM	4	9	7	9	0	1	9	12/1990	Paquette et al.	357	80	5/1988
	BN	4	6	6	3	2	4	0	5/1987	Hajdu et al.	428	545	11/1984
	BO	5	3	0	4	7	5	0	10/1994	Schubert et al.	181	294	8/1989
	BP	5	2	0	2	5	3	6	4/1993	Buonanno	174	35GC	2/1992
	BQ	4	0	8	9	5	7	5	5/1978	Grabbe	339	17	9/1976
	BR	5	1	5	1	7	7	0	9/1992	Inoue	357	53	11/1990
	BS	5	2	3	9	1	2	6	8/1993	Oshima	174	35	1/1991
	BT	5	2	5	0	8	4	5	10/1993	Runyan	257	729	11/1990
	BU	4	9	6	7	3	1	5	10/1990	Schelhorn	361	424	1/1990
	BV	5	7	7	0	3	0	4	6/1998	Nakamura	428	328	7/1995
	BW	4	6	6	1	8	3	7	4/1987	Sono	357	84	12/1985
	BX	4	8	3	9	7	1	6	6/1989	Butt	357	74	6/1987
	BY	4	9	5	3	0	0	2	8/1990	Nelson et al.	357	74	9/1989
	BZ	5	1	3	8	4	3	0	8/1992	Gow, 3 rd et al.	357	70	6/1991
	CA	5	1	4	9	6	6	2	9/1992	Eichelberger	437	8	2/1992
	CB	5	1	6	6	7	7	2	11/1992	Soldner et al.	257	659	2/1991
	CC	5	2	9	4	8	2	6	3/1994	Marcantonio, et al.	257	659	4/1993
	CD	4	9	3	5	1	7	4	6/1990	Suzuki	264	24	9/1989
	CE	5	0	4	7	2	6	0	9/1991	Durand	427	54.1	3/1990
	CF	5	1	8	0	5	1	3	1/1993	Durand	252	62.55	1/1990
	CG	5	4	2	4	2	5	1	6/1995	Sono et al.	437	214	9/1993
	CH	5	5	7	7	3	1	9	11/1996	Knecht	29	827	3/1995
	CI	5	5	8	9	1	2	9	12/1996	Kat et al.	264	437	6/1995
	CI	5	6	1	0	4	4	3	3/1997	Inagaki et al.	257	788	9/1995
	CK	4	6	8	7	6	2	2	8/1987	Longden	376	254	10/1985

	CL	5	6	7	2	9	1	8	9/1997	Kimbrough et al.	307	126	8/1994
	CM	5	3	8	4	4	7	7	1/1995	Bulucea et al.	257	372	3/1993
	CN	5	4	4	1	9	0	0	8/1995	Bulucea et al.	437	24	9/1994
	CO	5	5	5	2	3	3	8	9/1996	Kang	437	170	9/1995
	CP	5	7	1	4	1	0	2	2/1998	Highum et al.	264	105	4/1995
	CQ	5	8	6	4	0	8	8	1/1999	Sato et al.	174	35	1/1995
	CR	5	8	8	0	4	0	3	3/1999	Czajkowski et al.	174	35	1/1997
	CS	5	2	9	4	8	2	6	3/1994	Marcantonio et al.	257	659	4/1993

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	DI	"Electronics Packaging and Production", p 26-27
	DJ	"Electronic materials and Processes, Consulting and Short Courses", p 1-3
	DK	"Electronic Materials Handbook", p 470-483
	DL	"Electronic Packaging and Interconnection Handbook", p6.41-6.49
	DM	M.P. Baze et al., "Latch-Up Paths in Bipolar Integrated Circuits", IEEE Transactions on Nuclear Science, December 1986, Vol. NS-33. No. 6
	DN	A. H. Johnston, et al., "The Effect of Temperature on Single-Particle Latch-Up", IEEE Transactions on Nuclear Science, December 1991, Vol. 38, No. 6
	DO	SONG et al., "Parametric Investigation of Latch-Up Sensitivity in 1.25 μ m CMOS Technology", IEEE Transactions on Nuclear Science, December 1987, Vol. NS-34 No. 6
EXAMINER:		DATE CONSIDERED
EXAMINER: Initial if citation considered, whether or not citation is in conformance with MPEP §609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to the applicant.		

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: David R. Strobel,)
et al.)
Serial No: 08/372,289)
Filed: January 13, 1995)
Title: RADIATION SHIELDING OF)
INTEGRATED CIRCUITS AND)
MULTI-CHIP MODULES IN)
CERAMIC AND METAL PACKAGES)

Art Unit: 2503
Atty's
Docket: 551103

INFORMATION DISCLOSURE STATEMENT
PURSUANT TO 37 C.F.R. §§1.56 AND 1.97-98

Honorable Commissioner of Patents
and Trademarks
Washington, D.C. 20231

Dear Sir:

The citations listed on the enclosed PTO-1449 form are submitted under 37 C.F.R. §§1.97 and 1.98, and in compliance with the duty of disclosure as defined in 37 C.F.R. §1.56. The Examiner is requested to make these citations officially of

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the U.S. Postal Service as first-class mail in an envelope addressed to: Commissioner of Patents and Trademarks, Washington, D.C. 20231 on:

Date: 4-12-95

Signed: Bernard Klenk

record in the present patent application.

The Japanese Patent Publications cited on the enclosed Form - 1449 were made of record in the parent application Serial No. 08/221,506. Accordingly, copies of these references have not been submitted with this statement pursuant to 37 C.F.R. § 1.98(d).

All six of the references cited in the Form-1449 are in the Japanese language. Therefore, the Applicant is supplying the following concise explanations of relevance pursuant to 37 C.F.R. § 1.98(a)(3).

Japanese Patent Publications No. 60-180150 appears to disclose a semiconductor device enclosed within a plastic package, and surrounded by a thin metallic plating to absorb or collect unwanted electro-magnetic interference (EMI). The reference appears to concentrate on preventing malfunctions due to EMI, and does not appear to discuss spacecraft environment hazards, including high energy electron, proton and cosmic ray damage. The Applicant does not currently possess an English translation of this document.

Japanese Patent Publication No. 61-4249 appears to disclose a spot shielded semiconductor device which utilizes a single-layer shield film. The reference appears to concentrate on the use of a shield composed of a Cu-W alloy and does not appear to discuss a shielded semiconductor device which provides approximately 4pi protection for the semiconductor device. The

Applicant does not currently possess an English translation of this document.

Japanese Patent Publication No. 4-94560 appears to disclose a semiconductor device enclosed within a plastic package and surrounded by a grounded metallic plate to absorb or reflect EMI. The reference appears to concentrate on preventing malfunctions due to EMI, and does not appear to discuss spacecraft environment hazards, including high energy electron, proton and cosmic ray damage. The Applicant does not currently posses an English translation of this document.

Japanese Patent Publication No. 56-103452 appears to disclose a packaged semiconductor device having external leads connected to an internal semiconductor device protected from radiation by projections from a base portion. The reference appears to concentrate on the shielding projections to protect the semiconductor device from radiation which may penetrate a glass feed-through, and does not appear to discuss the increase in weight created by additional protective material. Thus, the reference does not appear to be adequate for space applications. The Applicant does not currently possess an English translation of this document.

Japanese Patent Publication No. 2-237053 appears to disclose a semiconductor device surrounded by an EMI wave absorber material in a metal package. The reference appears to concentrate on disposing the semiconductor device and the wave

absorber material within a recess in a dielectric material to reduce the amount of EMI radiation which strikes the semiconductor device. The reference does not appear to discuss protecting the semiconductor device from the hazards encountered in spacecraft environment. The Applicant does not currently possess an English translation of this document.

Japanese Patent Publication No. 62-125651 appears to disclose the use of spot shielding to protect a semiconductor device. The reference appears to concentrate on attaching a double-layered shield film to a sealing cover on an upper surface of the semiconductor package, and attaching another double-layered shield film to a lower surface of the package. The reference does not appear to discuss the use of a single-layer shield to reduce the weight of the semiconductor device, and to reduce the likelihood of the shield becoming dislodged from the semiconductor device during periods of high gravitational forces being applied to the device. The Applicant does not currently possess an English translation of this document.

The remaining reference cited on the enclosed Form - 1449, U.S. Patent 4,833,334 was not made of record in the parent application, Serial No. 08/221,506. Accordingly, a copy of this reference is being submitted with this Statement.

This Information Disclosure Statement is not to be construed as a representation that any one of the listed citations establishes, by itself or in combination with other information,

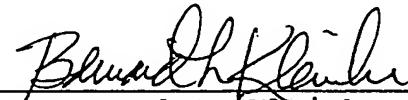
a prima facie case of unpatentability of any claim in the above-identified patent application. Additionally, this Information Disclosure Statement is not to be construed as a representation that a further search of the art has been made by the Applicant, or that additional information unknown to the Applicant and relevant to the examination of this patent application does not exist.

**AUTHORIZATION TO PAY AND PETITION
FOR THE ACCEPTANCE OF ANY NECESSARY FEES**

If any charges or fees must be paid in connection with the foregoing communication (including but not limited to the payment of an extension fee or issue fees), or if any overpayment is to be refunded in connection with the above-identified application, any such charges or fee, or any such overpayment may be respectively paid out of, or into, the Deposit Account No. 11-1240 of Bernard L. Kleinke. If any such payment also requires a Petition or Extension Request, please construe this authorization to pay as the necessary Petition or request which is required to accompany the payment.

Dated: April 12, 1995

Respectfully submitted,
LAFF, WHITESEL, CONTE & SARET

By 
Bernard L. Kleinke
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FORM PTO-1449 (REV. 7-80)		U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				ATTY. DOCKET NO.	SERIAL NO.		
LIST OF PRIOR ART CITED BY APPLICANT (Use several sheets if necessary)						551103	08/372,289		
						APPLICANT	David J. Strobel		
						FILING DATE	GROUP		
				Jan. 13, 1995	2503				
U.S. PATENT DOCUMENTS									
*EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME			CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA	4 8 3 3 3 3 4	5/23/89	Valy, et al.					
	AB								
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FOREIGN PATENT DOCUMENTS									
		DOCUMENT NUMBER	DATE	COUNTRY			CLASS	SUBCLASS	TRANSLATION
	AL	6 0 1 3 0 1 5 0	9/85	Japan			257	660	YES
	AM	6 1 0 0 4 2 4 9	1/86	Japan			257	659	NO
	AN	0 4 0 9 4 5 6 0	3/92	Japan			257	660	
	AO	5 6 1 0 3 4 5 2	8/81	Japan			257	660	
	AP	0 2 2 3 7 0 5 3	9/90	Japan			257	659	
OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)									
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	AS								
	AT								
EXAMINER					DATE CONSIDERED				
<p>*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.</p>									

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4-12-95

Bernard L. Klein

LAFF, WHITESEL, CONTE & SARET
Intellectual Property Law
101 West Broadway, Suite 1580
San Diego, California 92101

Phone: (619) 232-6060

U.S. DEPARTMENT OF COMMERCE PATENT AND TRADEMARK OFFICE				ATTY. DOCKET NO.	SERIAL NO.			
				551103	08/372,289			
LIST OF PRIOR ART CITED BY APPLICANT (Use several sheets if necessary)				APPLICANT				
				David J. Strobel, et al.				
				FILING DATE	GROUP			
				Jan. 13, 1995	2503			
U.S. PATENT DOCUMENTS								
EXAMINER INITIAL		DOCUMENT NUMBER	DATE	NAME		CLASS	SUBCLASS	FILING DATE IF APPROPRIATE
	AA							
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FOREIGN PATENT DOCUMENTS								
		DOCUMENT NUMBER	DATE	COUNTRY		CLASS	SUBCLASS	TRANSLATION
								YES NO
AL	6 2	1 2 5 6 5 1	6/87	Japan		257	660	
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OTHER PRIOR ART (Including Author, Title, Date, Pertinent Pages, Etc.)								
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*EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; Draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.								

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LAFF, WHITESELL, CONTE & SARET
Intellectual Property Law
101 West Broadway, Suite 1580
San Diego, California 92101

Phone: (619) 232-6060

Notice of References Cited

Application/Control No.
09/878,683

Applicant(s)/Patent Under Reexam

Czjakowski et al

Examiner

Hung V. Ngo

Art Unit

2831

Page 1 of 1

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	Document Number Country Code-Number-Kind Code	Date MM-YYYY ¹	Name	Classification ²	
A	4,639,826	1/1987	Val et al	361	272
B					
C					
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FOREIGN PATENT DOCUMENTS

	Document Number Country Code-Number-Kind Code	Date MM-YYYY ¹	Country	Name	Classification ²	
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NON-PATENT DOCUMENTS

	Include, as applicable: Author, Title, Date, Publisher, Edition or Volume, Pertinent Pages
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¹ A copy of this reference is not being furnished with this Office action. See MPEP § 707.05(a).

¹ Dates in MM-YYYY format are publication dates.

² Classifications may be U.S. or foreign.

Notice of References Cited

Application No.
08/788,134

Applicant(s)

Czajkowski et al

Examiner

Hung V. Ngo

Group Art Unit
2109

Page 1 of 1

U.S. PATENT DOCUMENTS

	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	5,635,754	04-01-94	Strobel et al	257	659
B	4,089,575	05-16-78	Grabbe	439	71
C	4,506,108	03-19-85	Kersch et al	174	52.4
D					
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	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
N	04-273200	07 92	JP	MURAKI	—	—
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NON-PATENT DOCUMENTS

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<i>Notice of References Cited</i>			Application No.	Applicant(s)		
			08/788,134	Czejkowski et al		
			Examiner	Group Art Unit		
			Hung V Ngo	2109	Page 1 of 1	
U.S. PATENT DOCUMENTS						
	DOCUMENT NO.	DATE	NAME		CLASS	SUBCLASS
A	5,239,126	08-24-93	Oshiba		174	35r
B	5,406,117	04-11-95	Dlugokecki et al		257	659
C	5,250,845	10-15-93	Runyan		257	729
D	4,967,315	10-30-90	Schelhorn		361	424
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FOREIGN PATENT DOCUMENTS						
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Notice of References Cited			Application No. 09/109,954	Applicant(s) Czajkowski et al		
			Examiner Hung V Ngo	Group Art Unit 2831	Page 1 of 1	
U.S. PATENT DOCUMENTS						
	DOCUMENT NO.	DATE	NAME		CLASS	SUBCLASS
A	5,239,126	08-24-93	Oshiba		174	35r
B	5,406,117	04-11-95	Dlugokecki et al		257	659
C	5,250,845	10-15-93	Runyan		257	729
D	4,967,315	10-30-90	Schelhorn		361	818
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Notice of References Cited

Application No. 09/109,954	Applicant(s) Czajkowski et al
Examiner Hung V Ngo	Group Art Unit 2831

Page 1 of 1

U.S. PATENT DOCUMENTS

	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	5,151,770	09-29-92	Inoue	257	659
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FOREIGN PATENT DOCUMENTS

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NON-PATENT DOCUMENTS

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Notice of References Cited

Application No. 09/109,954	Applicant(s) Czajkowski et al
Examiner Hung V Ngo	Group Art Unit 2831

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U.S. PATENT DOCUMENTS

	DOCUMENT NO.	DATE	NAME	CLASS	SUBCLASS
A	4,167,647	9/1979	Salera	174	52.4
B					
C					
D					
E					
F					
G					
H					
I					
J					
K					
L					
M					

FOREIGN PATENT DOCUMENTS

	DOCUMENT NO.	DATE	COUNTRY	NAME	CLASS	SUBCLASS
N						
O						
P						
Q						
R						
S						
T						

NON-PATENT DOCUMENTS

	DOCUMENT (Including Author, Title, Source, and Pertinent Pages)	DATE
U		
V		
W		
X		